

Title (en)  
Connection arrangement on circuit boards

Title (de)  
Verbindungsanordnung an Leiterplatten

Title (fr)  
Agencement de connexion sur des plaques conductrices

Publication  
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Application  
**EP 09760781 A 20091202**

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Abstract (en)  
[origin: WO2010063459A1] The invention relates to a connection assembly, comprising a plug element which has at least one pluggable spring-type contact element, particularly a plurality of pluggable spring-type contact elements, having a reversible deflection characteristic, and comprising a circuit board having plated-through bore holes that are arranged in an arrangement corresponding to the arrangement of the contact element or the contact elements of the plug element, wherein the bore holes and the contact element that can be plugged into them, or the contact elements that can be plugged into them, are matched to one another such that the plug element can be connected to the circuit board and removed by hand by inserting the contact element or the contact elements into the bore holes, wherein the connection assembly has a vibration-resistant mechanical safeguard against unintentional removal of the plug element from the circuit board.

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IPC 8 full level  
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**H01R 4/184** (2013.01 - EP US); **H01R 12/515** (2013.01 - EP US); **H01R 12/58** (2013.01 - EP US)

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See references of WO 2010063459A1

Cited by  
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